

- ☐ Tentative Specification  
☐ Preliminary Specification  
☒ Approval Specification

MODEL NO.: G215HCJ  
SUFFIX: LH1

**Customer:**

**APPROVED BY**

**SIGNATURE**

**Name / Title**

Note

Please return 1 copy for your confirmation with your signature and comments.

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## CONTENTS

<b>1. GENERAL DESCRIPTION .....</b>	<b>5</b>
1.1 OVERVIEW .....	5
1.2 FEATURE .....	5
1.3 APPLICATION .....	5
1.4 GENERAL SPECIFICATIONS .....	5
1.5 MECHANICAL SPECIFICATIONS .....	5
<b>2. ABSOLUTE MAXIMUM RATINGS .....</b>	<b>6</b>
2.1 ABSOLUTE RATINGS OF ENVIRONMENT .....	6
2.2 ELECTRICAL ABSOLUTE RATINGS .....	7
2.2.1 TFT LCD MODULE .....	7
2.2.2 BACKLIGHT UNIT .....	7
<b>3. ELECTRICAL CHARACTERISTICS .....</b>	<b>8</b>
3.1 TFT LCD MODULE .....	8
3.2 BACKLIGHT UNIT .....	9
<b>4. BLOCK DIAGRAM .....</b>	<b>11</b>
4.1 TFT LCD MODULE .....	11
<b>5. INPUT TERMINAL PIN ASSIGNMENT .....</b>	<b>12</b>
5.1 TFT LCD MODULE .....	12
5.2 BACKLIGHT UNIT(Converter connector pin).....	13
5.3 COLOR DATA INPUT ASSIGNMENT .....	14
<b>6. INTERFACE TIMING .....</b>	<b>15</b>
6.1 INPUT SIGNAL TIMING SPECIFICATIONS .....	15
6.2 POWER ON/OFF SEQUENCE.....	17
6.3 SCANNING DIRECTION .....	19
<b>7. OPTICAL CHARACTERISTICS .....</b>	<b>20</b>
7.1 TEST CONDITIONS .....	20
7.2 OPTICAL SPECIFICATIONS .....	20
<b>8. RELIABILITY TEST CRITERIA .....</b>	<b>23</b>
<b>9. PACKAGING.....</b>	<b>24</b>
9.1 PACKING SPECIFICATIONS .....	24
9.2 PACKING METHOD .....	24
9.3 UN-PACKING METHOD .....	26
<b>10. DEFINITION OF LABELS.....</b>	<b>27</b>
10.1 INX MODULE LABEL .....	27
<b>11. PRECAUTIONS .....</b>	<b>28</b>
11.1 ASSEMBLY AND HANDLING PRECAUTIONS.....	28
11.2 STORAGE PRECAUTIONS.....	28

11.3 OTHER PRECAUTIONS.....	29
<b>12. MECHANICAL CHARACTERISTICS .....</b>	<b>30</b>
<b>Appendix. SYSTEM COVER DESIGN NOTICE .....</b>	<b>32</b>

## REVISION HISTORY

Version	Date	Page	Description
0.0	2023.Jan.17	All	Tentative Specification was first issued.
1.0	2023.Sep.11	All	Preliminary Specification was first issued.
2.0	2024.Jan.8	All	Approval Specification was first issued.

## 1. GENERAL DESCRIPTION

### 1.1 OVERVIEW

G215HCJ-LH1 is a 21.5" TFT Liquid Crystal Display IA module with WLED Backlight unit and 30 pins 2ch-LVDS interface. This module supports 1920 x 1080 Full HD mode and can display up to 16.7M colors. The converter module for Backlight is built in.

### 1.2 FEATURE

- FHD (1920 x 1080 pixels) resolution
- Wide operating temperature.
- RoHS compliance

### 1.3 APPLICATION

- TFT LCD Monitor
- Factory Application
- Amusement

### 1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	476.6 (H) x 268.1(V) (21.5" diagonal)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	1920 x R.G.B x 1080	pixel	-
Pixel Pitch	0.248(H) x 0.248(W)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	16.7M	color	-
Display Mode	Normally Black	-	-
Surface Treatment	Hard Coating (2H), Anti-Glare	-	-
Module Power Consumption	44( Panel 4 + CNV:40)	W	Typ.

### 1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Typ.	Max.	Unit	Note
Module Size	Horizontal(H)	495.1	495.6	496.1	mm	(1)
	Vertical(V)	291.7	292.2	292.7	mm	
	Depth(D)	23.55	24.05	24.55	mm	
Bezel Area	Horizontal	479.34	479.84	480.34	mm	-
	Vertical	270.81	271.31	271.81	mm	
Active Area	Horizontal	-	476.64	-	mm	
	Vertical	-	268.11	-	mm	
Weight		1493	1571	1650	g	

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

## 2. ABSOLUTE MAXIMUM RATINGS

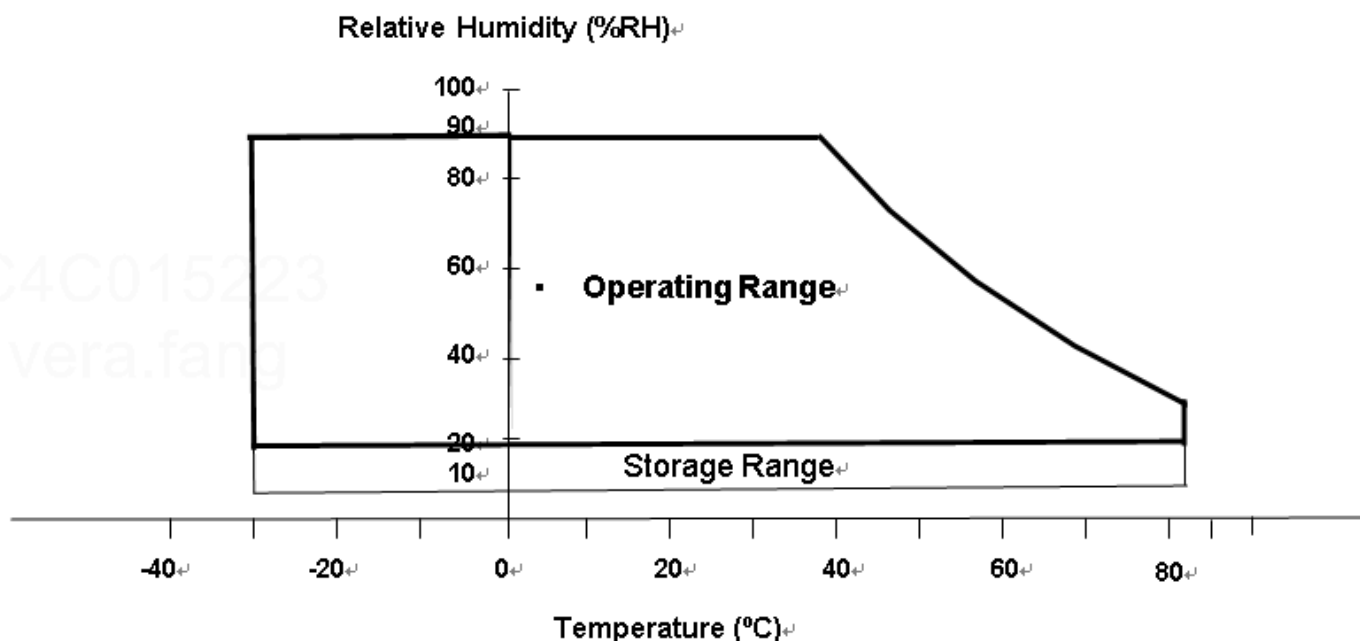
### 2.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Operating Ambient Temperature	T <sub>OP</sub>	-30	+80	°C	(1)(2)
Storage Temperature	T <sub>ST</sub>	-30	+80	°C	

Note (1) Temperature and relative humidity range is shown in the figure below

- (a) 90 %RH Max.
- (b) Wet-bulb temperature should be 39 °C Max.
- (c) No condensation.

Note (2) Panel surface temperature should be 0°C min. and 80°C max under V<sub>CC</sub>=5.0V, f<sub>r</sub> =60Hz, typical LED string current, 25°C ambient temperature, and no humidity control . Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than 80 °C .(Panel surface temperature)



## 2.2 ELECTRICAL ABSOLUTE RATINGS

### 2.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Power Supply Voltage	VCC	-0.3	6.0	V	(1)
Logic Input Voltage	V <sub>IN</sub>	-0.3	3.6	V	

### 2.2.2 BACKLIGHT UNIT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Converter Voltage	V <sub>i</sub>	-0.3	18	V	(1) , (2)
Enable Voltage	EN	-0.3	5.5	V	
Backlight Adjust	Dimming	-0.3	5.5	V	

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for LED (Refer to 3.2 for further information).

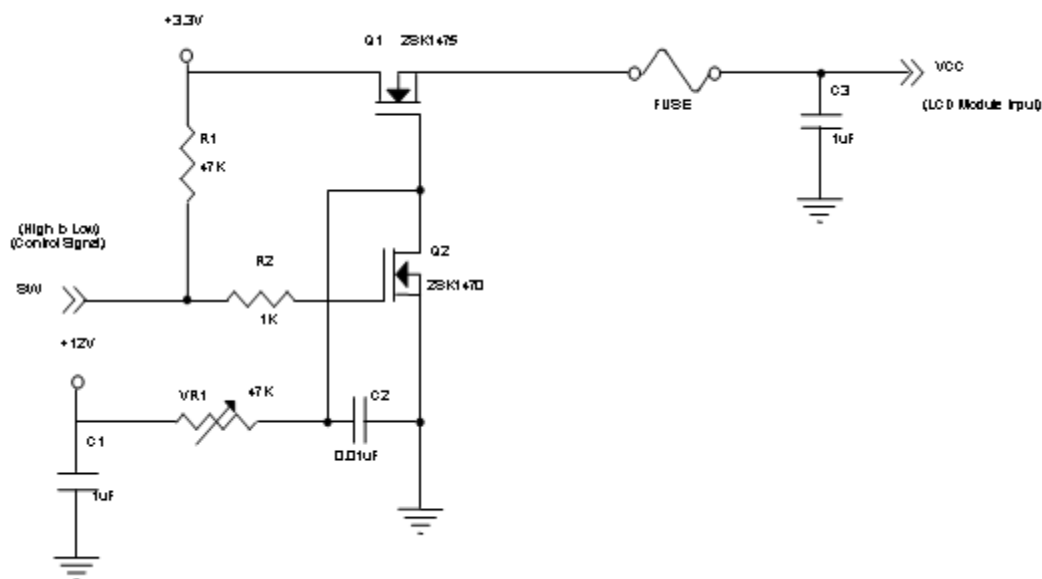
## 3. ELECTRICAL CHARACTERISTICS

### 3.1 TFT LCD MODULE

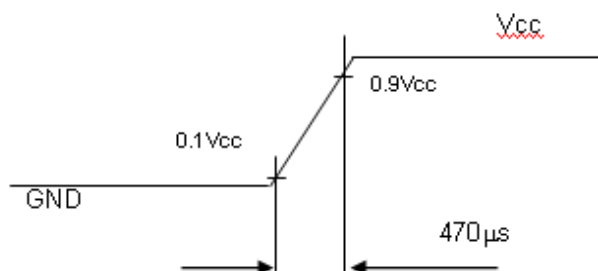
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{CC}$	4.5	5.0	5.5	V	-
Ripple Voltage	$V_{RP}$	-	-	300	mVp-p	
Inrush Current	$I_{INRUSH}$	-	-	3.0	A	(2)
Power Supply Current	White	-	0.8	0.96	A	(3)a
	Black	-	0.4	0.48	A	(3)b
	Vertical Stripe	-	0.6	0.73	A	(3)c
LVDS differential input voltage	$V_{id}$	100	-	600	mV	
LVDS common input voltage	$V_{ic}$	1.0	1.2	1.4	V	
Differential Input Voltage for LVDS Receiver Threshold	"H" Level	$V_{IH}$	-	100	mV	-
	"L" Level	$V_{IL}$	-100	-	mV	-
Terminating Resistor	$R_T$	-	100	-	Ohm	-

Note (1) The module should be always operated within above ranges.

Note (2) Measurement Conditions:

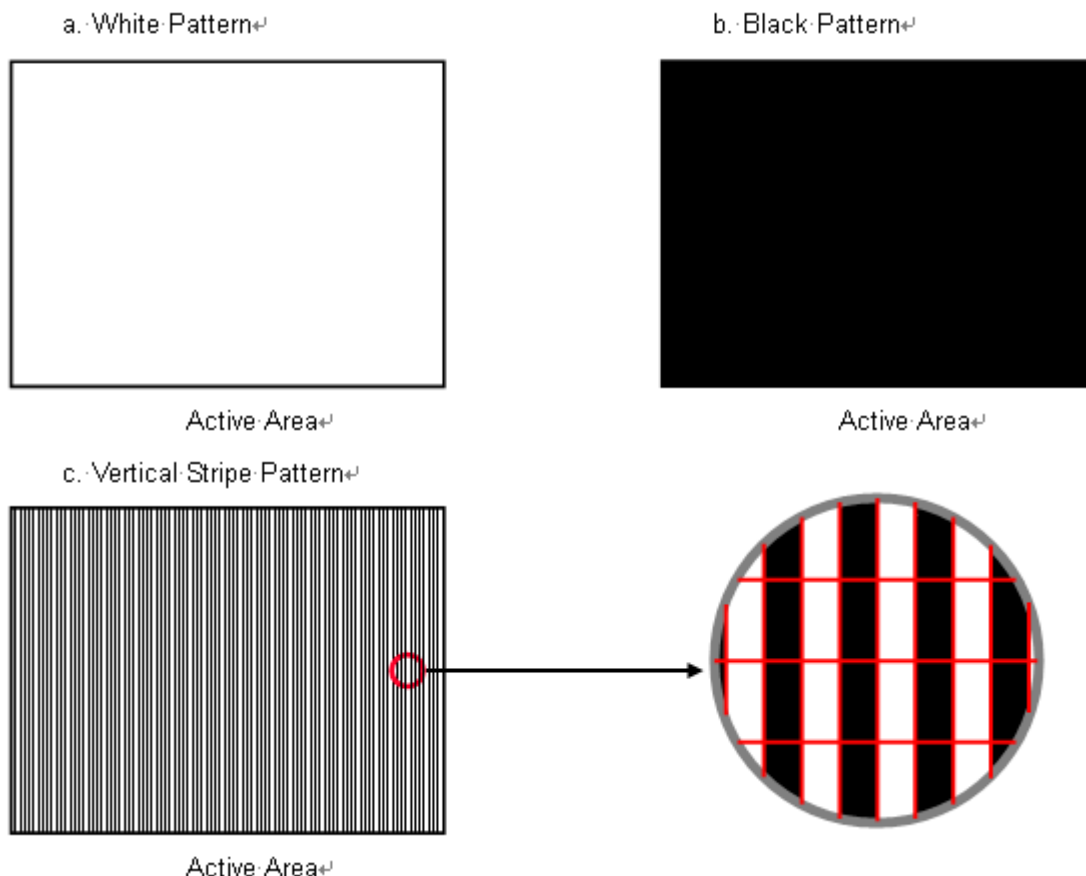


**Vcc rising time is 470μs**





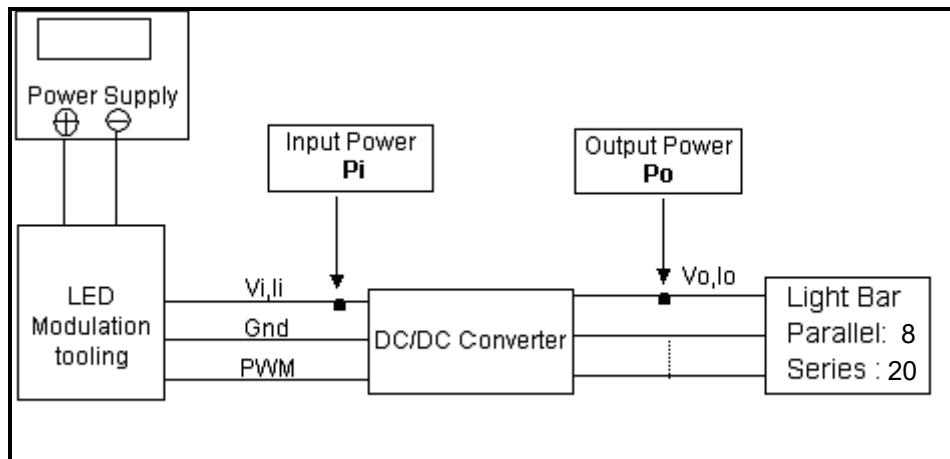
Note (3) The specified power supply current is under the conditions at  $V_{CC} = 5V$ ,  $T_a = 25 \pm 2^\circ C$ , DC Current and  $f_v = 60$  Hz, whereas a power dissipation check pattern below is displayed.



## 3.2 BACKLIGHT UNIT

Parameter		Symbol	Value			Unit	Note
			Min.	Typ.	Max.		
Converter Input Voltage		$V_i$	10.8	12.0	13.2	$V_{DC}$	(Duty 100%)
Converter Input Ripple Voltage		$V_{IRP}$	-	-	500	mV	
Converter Input Current		$I_i$	2.6	3.3	4.0	A <sub>DC</sub>	@ $V_i = 12V$ (Duty 100%)
Converter Inrush Current		$I_{IRUSH}$	-	-	10.0	A	@ $V_i$ rising time=10ms ( $V_i=12V$ )
Input Power Consumption		$P_i$	-	40	48	W	(1)
EN Control Level	Backlight on	ENLED (BLON)	2.0	3.3	5.0	V	
	Backlight off		0	-	0.3	V	
PWM Control Level	PWM High Level	Dimming (E_PWM)	2.0	-	5.0	V	
	PWM Low Level		0	-	0.15	V	
PWN Noise Range		$V_{Noise}$	-	-	0.1	V	
PWM Control Frequency		$f_{PWM}$	190	200	20k	Hz	(3)
PWM Dimming Control Duty Ratio		-	5	-	100	%	(3), @ 190Hz < $f_{PWM}$ < 1kHz
			20	-	100	%	(2), @ 1kHz ≤ $f_{PWM}$ < 20kHz
LED Life Time		$L_{LED}$	50,000		-	Hrs	(2)

Note (1) LED current is measured by utilizing a high frequency current meter as shown below:



Note (2) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at  $T_a = 25 \pm 2^\circ\text{C}$  and Duty 100% until the brightness becomes  $\leq 50\%$  of its original value. Operating LED at high temperature condition will reduce life time and lead to color shift.

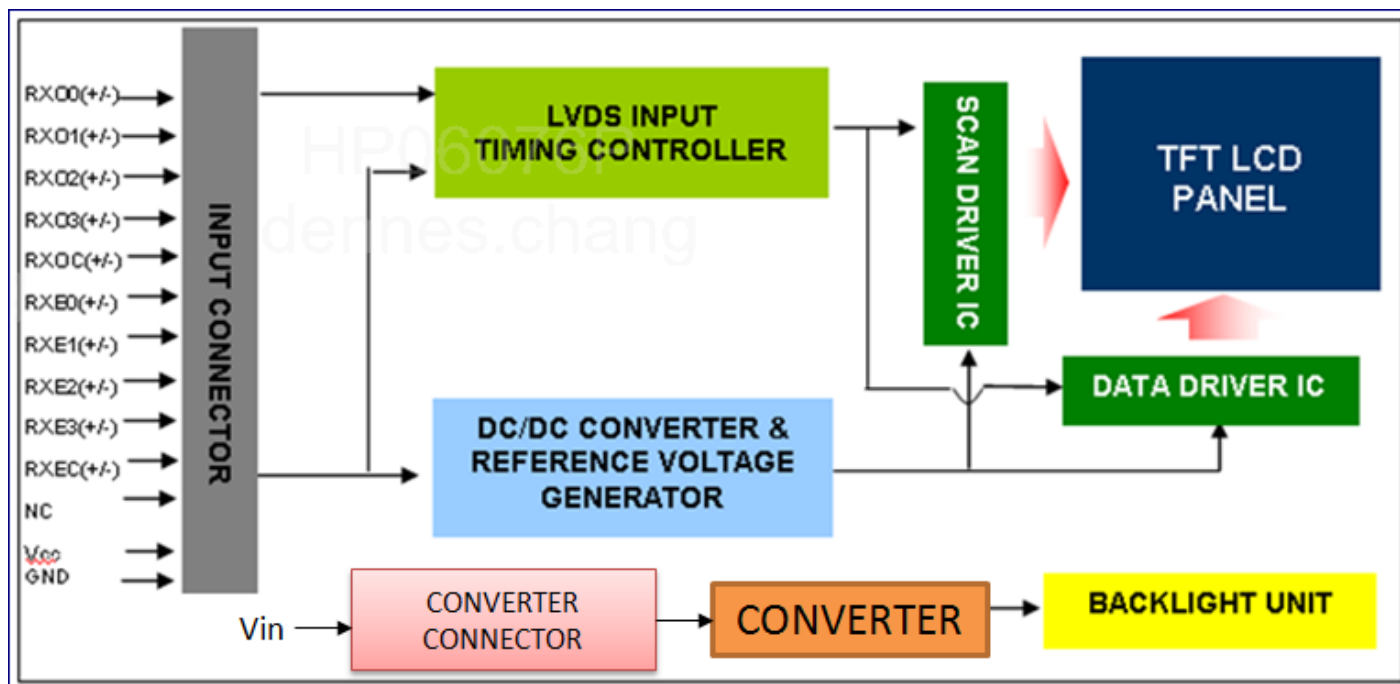
Note (3) At 190 ~1kHz PWM control frequency, duty ratio range is restricted from 5% to 100%.

1K ~20kHz PWM control frequency, duty ratio range is restricted from 20% to 100%.

If PWM control frequency is applied in the range from 1KHz to 20KHZ, The “non-linear” phenomenon on the Backlight Unit may be found. So It's a **suggestion** that PWM control frequency should be **less than 1KHz**.

## 4. BLOCK DIAGRAM

### 4.1 TFT LCD MODULE



## 5. INPUT TERMINAL PIN ASSIGNMENT

### 5.1 TFT LCD MODULE

Pin	Name	Description
1	RXO0-	Negative LVDS differential data input. Channel O0 (odd)
2	RXO0+	Positive LVDS differential data input. Channel O0 (odd)
3	RXO1-	Negative LVDS differential data input. Channel O1 (odd)
4	RXO1+	Positive LVDS differential data input. Channel O1 (odd)
5	RXO2-	Negative LVDS differential data input. Channel O2 (odd)
6	RXO2+	Positive LVDS differential data input. Channel O2 (odd)
7	GND	Ground
8	RXOC-	Negative LVDS differential clock input. (odd)
9	RXOC+	Positive LVDS differential clock input. (odd)
10	RXO3-	Negative LVDS differential data input. Channel O3(odd)
11	RXO3+	Positive LVDS differential data input. Channel O3 (odd)
12	RXE0-	Negative LVDS differential data input. Channel E0 (even)
13	RXE0+	Positive LVDS differential data input. Channel E0 (even)
14	GND	Ground
15	RXE1-	Negative LVDS differential data input. Channel E1 (even)
16	RXE1+	Positive LVDS differential data input. Channel E1 (even)
17	GND	Ground
18	RXE2-	Negative LVDS differential data input. Channel E2 (even)
19	RXE2+	Positive LVDS differential data input. Channel E2 (even)
20	RXEC-	Negative LVDS differential clock input. (even)
21	RXEC+	Positive LVDS differential clock input. (even)
22	RXE3-	Negative LVDS differential data input. Channel E3 (even)
23	RXE3+	Positive LVDS differential data input. Channel E3 (even)
24	GND	Ground
25	NC	For LCD internal use only, Do not connect
26	NC	For LCD internal use only, Do not connect
27	NC	For LCD internal use only, Do not connect
28	Vcc	+5.0V power supply
29	Vcc	+5.0V power supply
30	Vcc	+5.0V power supply

Note (1) Connector Part No.: FCN: WF13-428-3033 or P-TWO: 187098-30091 or equivalent..

Note (2) User's connector Part No.:

Mating Wire Cable Connector Part No.: FI-X30H(JAE) or FI-X30HL(JAE)

Mating FFC Cable Connector Part No.: 217007-013001 (P-TWO) or JF05X030-1 (JAE).

Note (3) "Low" stands for 0V. "High" stands for 3.3V. "NC" stands for "No Connection".

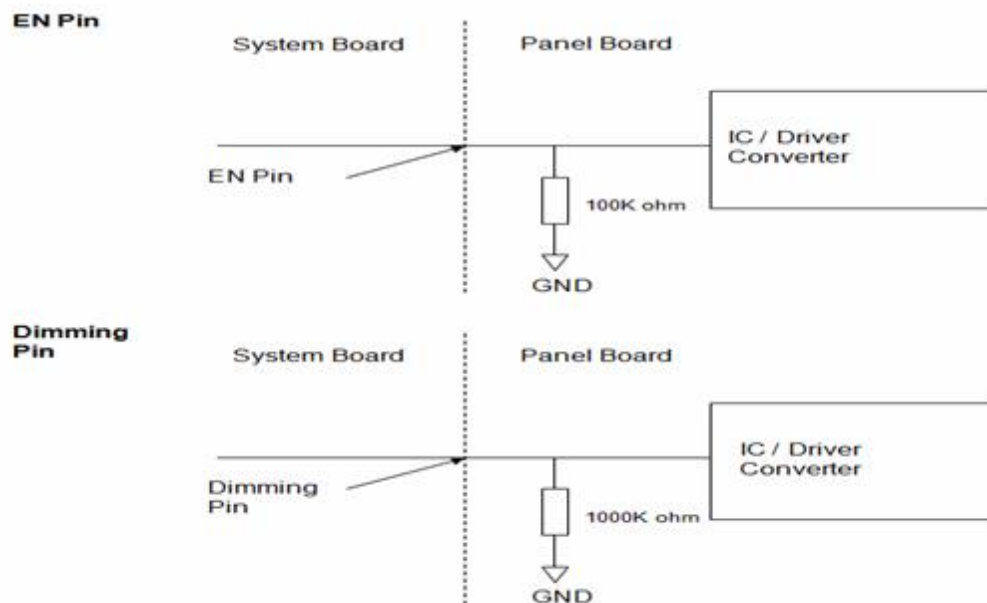
Note (4) Pin25, Pin26, Pin27 input signals should be set to no connection, this module would operate normally.

## 5.2 BACKLIGHT UNIT(Converter connector pin)

Pin	Symbol	Description	Remark
1	$V_i$	Converter input voltage	12V
2	$V_i$	Converter input voltage	12V
3	$V_i$	Converter input voltage	12V
4	$V_i$	Converter input voltage	12V
5	$V_{GND}$	Converter ground	Ground
6	$V_{GND}$	Converter ground	Ground
7	$V_{GND}$	Converter ground	Ground
8	$V_{GND}$	Converter ground	Ground
9	EN	Enable pin	3.3V
10	Dimming	Backlight Adjust	PWM Dimming (Hi: 3.3V <sub>DC</sub> , Lo: 0V <sub>DC</sub> )

Note (1)Connector Part No.: CI0110M1HR0-NH (Cvilux) or equivalent.

Note (2)User's connector Part No.: Cvilux CI01 or equivalent



## 5.3 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

Color		Data Signal																							
		Red								Green								Blue							
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
Basic Colors	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Gray Scale Of Red	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray Scale Of Green	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	Green(253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
	Green(254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green(255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Gray Scale Of Blue	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

Note (1)0: Low Level Voltage, 1: High Level Voltage

## 6. INTERFACE TIMING

### 6.1 INPUT SIGNAL TIMING SPECIFICATIONS

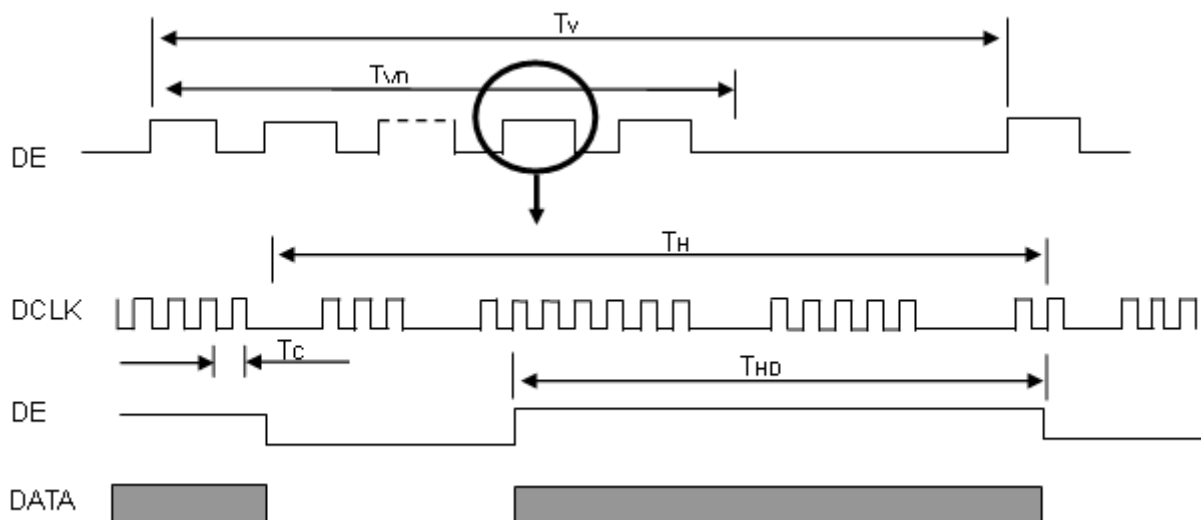
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
LVDS Clock	Frequency	F <sub>c</sub>	58.54	74.25	97.98	MHz	-
	Period	T <sub>c</sub>	-	13.47	-	ns	
	Input cycle to cycle jitter	T <sub>rd</sub>	---	---	200	ns	(a)
	Input Clock to data skew	TLVCCS	-0.02*T <sub>c</sub>	-	0.02*T <sub>c</sub>	ps	(b)
	Spread spectrum modulation range	F <sub>clkin_mod</sub>	0.987*F <sub>c</sub>	---	1.013*F <sub>c</sub>	MHz	(c)
	Spread spectrum modulation frequency	F <sub>SSM</sub>	---	---	200	KHz	
Vertical Display Term	Frame Rate	Fr	50	60	75	Hz	T <sub>v</sub> =T <sub>vd</sub> +T <sub>vb</sub>
	Total	T <sub>v</sub>	1110	1125	1220	Th	-
	Active Display	T <sub>vd</sub>	1080	1080	1080	Th	-
	Blank	T <sub>vb</sub>	T <sub>v</sub> -T <sub>vd</sub>	45	T <sub>v</sub> -T <sub>vd</sub>	Th	-
Horizontal Display Term	Total	T <sub>h</sub>	1050	1100	1150	Tc	T <sub>h</sub> =T <sub>hd</sub> +T <sub>hb</sub>
	Active Display	T <sub>hd</sub>	960	960	960	Tc	-
	Blank	T <sub>hb</sub>	T <sub>h</sub> -T <sub>hd</sub>	140	T <sub>h</sub> -T <sub>hd</sub>	Tc	-

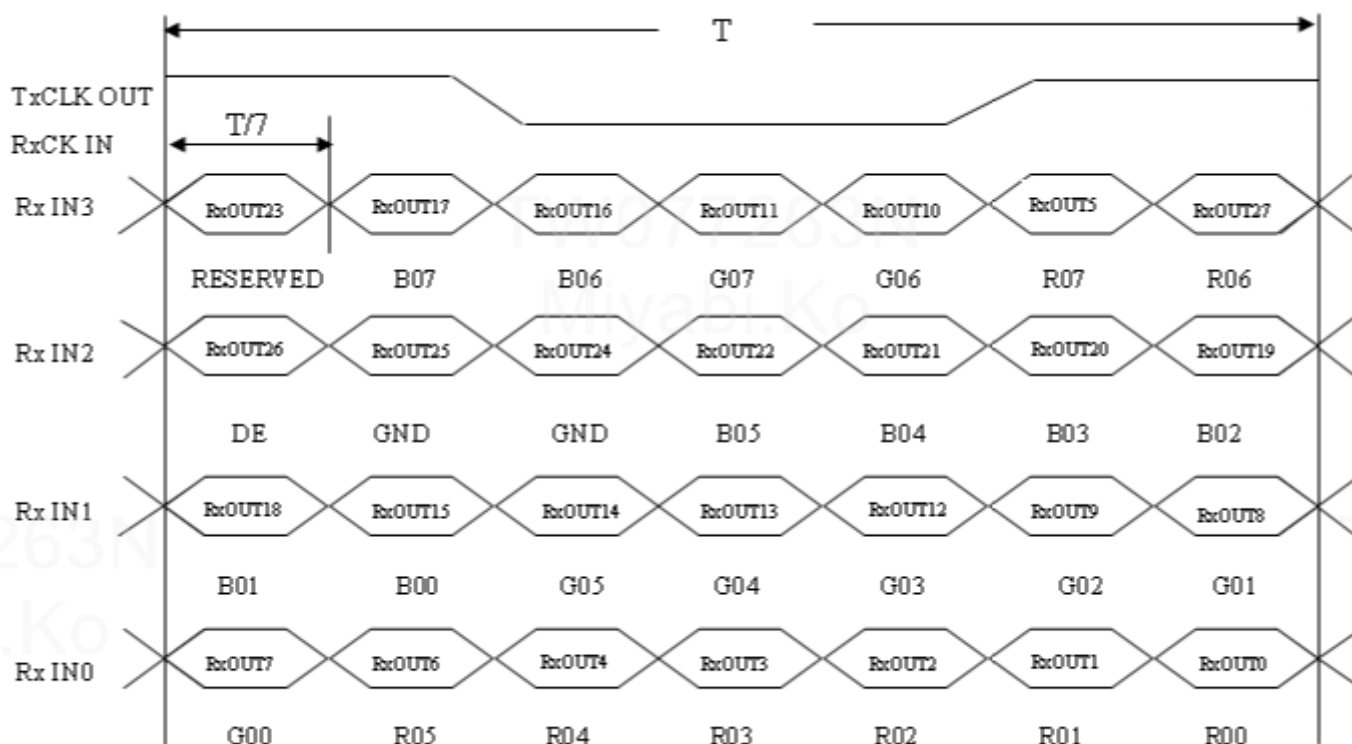
Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

Note (2) The T<sub>v</sub>(T<sub>vd</sub>+T<sub>vb</sub>) must be integer, otherwise, the module would operate abnormally.

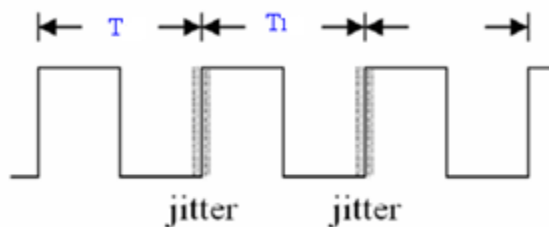
#### INPUT SIGNAL TIMING DIAGRAM



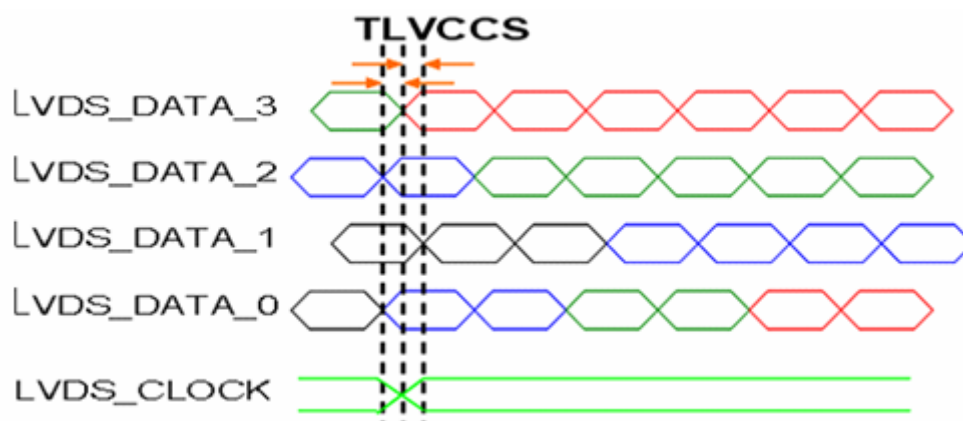
## TIMING DIAGRAM of LVDS



Note (a) The input clock cycle-to-cycle jitter is defined as below figures.  $T_{rdl} = |T_1 - T_1|$

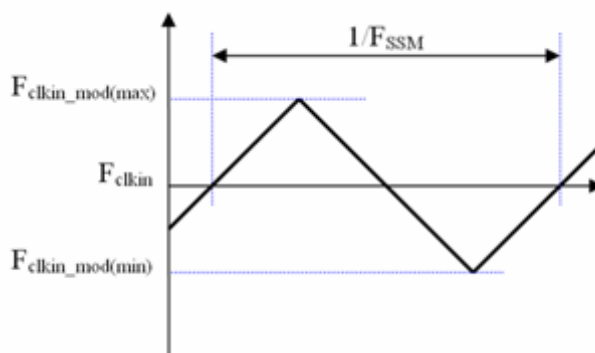


Note (b) Input Clock to data skew is defined as below figures.



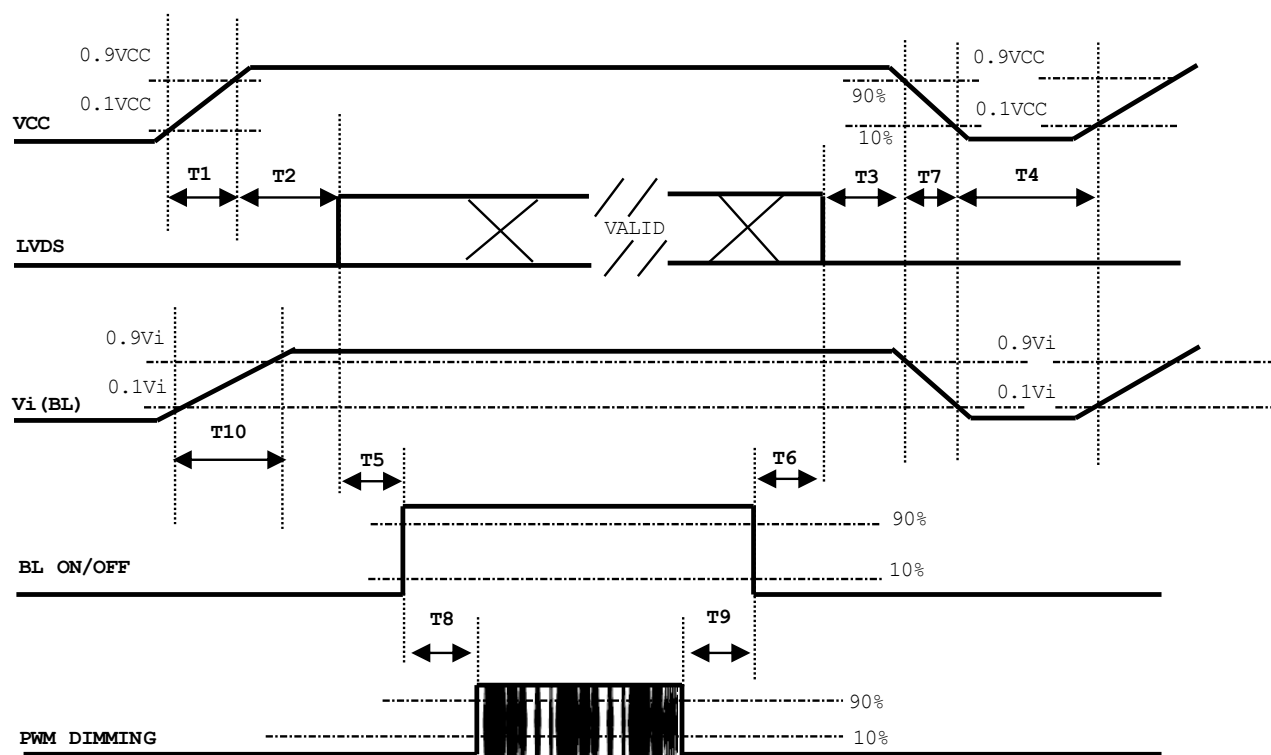


Note (c) The SSCG (Spread spectrum clock generator) is defined as below figures.



## 6.2 POWER ON/OFF SEQUENCE

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



Parameter	Value			Units
	Min	Typ	Max	
T1	0.5	-	10	ms
T2	0	-	50	ms
T3	0	-	50	ms
T4	500	-	-	ms
T5	450	-	-	ms
T6	200	-	-	ms
T7	10	-	100	ms
T8	10	-	-	ms
T9	10	-	-	ms
T10	20	-	50	ms

**Note:**

- (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.
- (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.
- (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.
- (4) T4 should be measured after the module has been fully discharged between power off and on period.
- (5) Interface signal shall not be kept at high impedance when the power is on.
- (6) INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.
- (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "T7 spec".

### 6.3 SCANNING DIRECTION

The following figures show the image see from the front view. The arrow indicates the direction of scan.



PCBA on the top side

## 7. OPTICAL CHARACTERISTICS

### 7.1 TEST CONDITIONS

Item	Symbol	Value	Unit
Ambient Temperature	Ta	25±2	°C
Ambient Humidity	Ha	50±10	%RH
Supply Voltage	According to typical value and tolerance in "ELECTRICAL CHARACTERISTICS"		
Input Signal			
PWM Duty Ratio	D	100	%

### 7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown here and all items are measured at the center point of screen unless otherwise noted. The following items should be measured under the test conditions described above and stable conditions shown in Note (5).

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Color Chromaticity	Red	Rx	$\theta X=0^{\circ}, \theta Y=0^{\circ}$ Grayscale Maximum	0.602	0.652	0.702	-	(1), (5)
		Ry		0.288	0.338	0.388		
	Green	Gx		0.280	0.330	0.380		
		Gy		0.559	0.609	0.659		
	Blue	Bx		0.101	0.151	0.201		
		By		0.004	0.054	0.104		
	White	Wx		0.263	0.313	0.363		
		Wy		0.279	0.329	0.379		
	Center Luminance of White			LC	1120	1400		
Contrast Ratio		CR	800	1000			(2), (5)	
Response Time		TR	$\theta X=0^{\circ}, \theta Y=0^{\circ}$	-	13	18	-	(3)
		TF		-	12	17	-	
White Variation		$\delta W$	$\theta X=0^{\circ}, \theta Y=0^{\circ}$	75	80	-	%	(5), (6)
Viewing Angle	Horizontal	$\theta X+$	$CR \geq 10$	80	89	-	Deg.	(1), (5)
		$\theta X-$		80	89	-		
	Vertical	$\theta Y+$		80	89	-		
		$\theta Y-$		80	89	-		

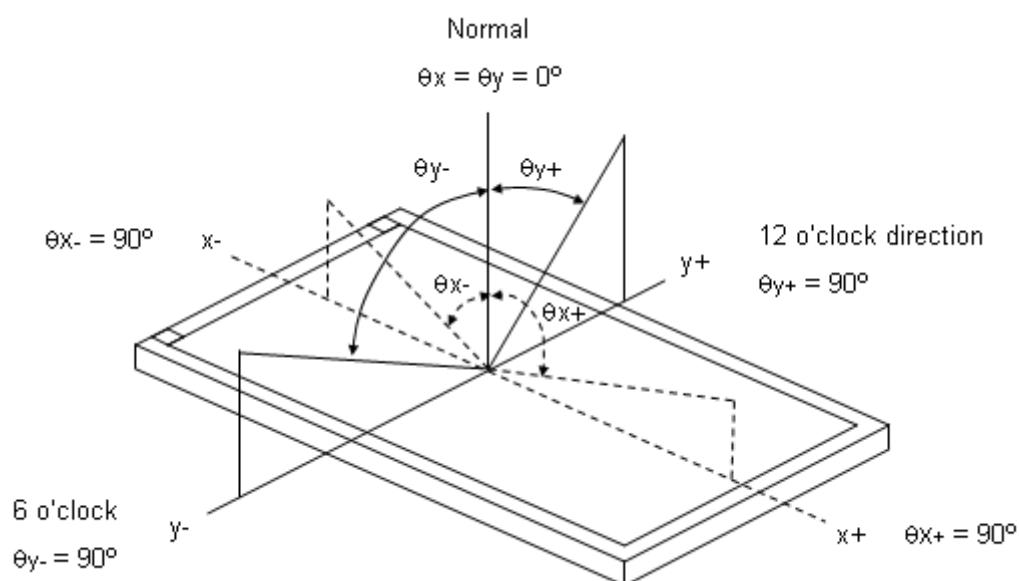
Definition :

Grayscale Maximum : Grayscale 255 (10 bits: grayscale 1023 ; 8 bits : grayscale 255 ; 6 bits: grayscale 63)

White : Luminance of Grayscale Maximum (All R,G,B)

Black : Luminance of grayscale 0 (All R,G,B)

Note (1) Definition of Viewing Angle ( $\theta_x$ ,  $\theta_y$ ):

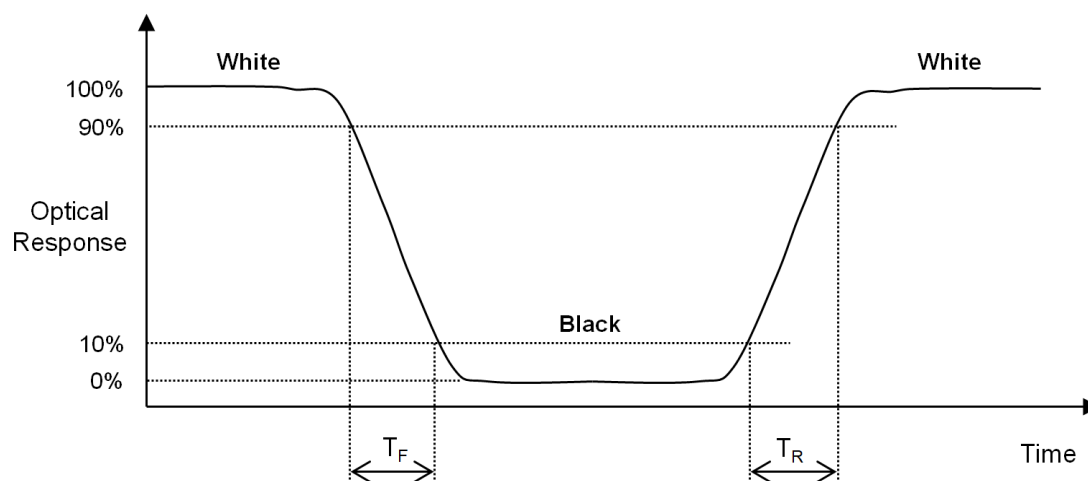


Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression at center point.

$$\text{Contrast Ratio (CR)} = \text{White} / \text{Black}$$

Note (3) Definition of Response Time ( $T_R$ ,  $T_F$ ):

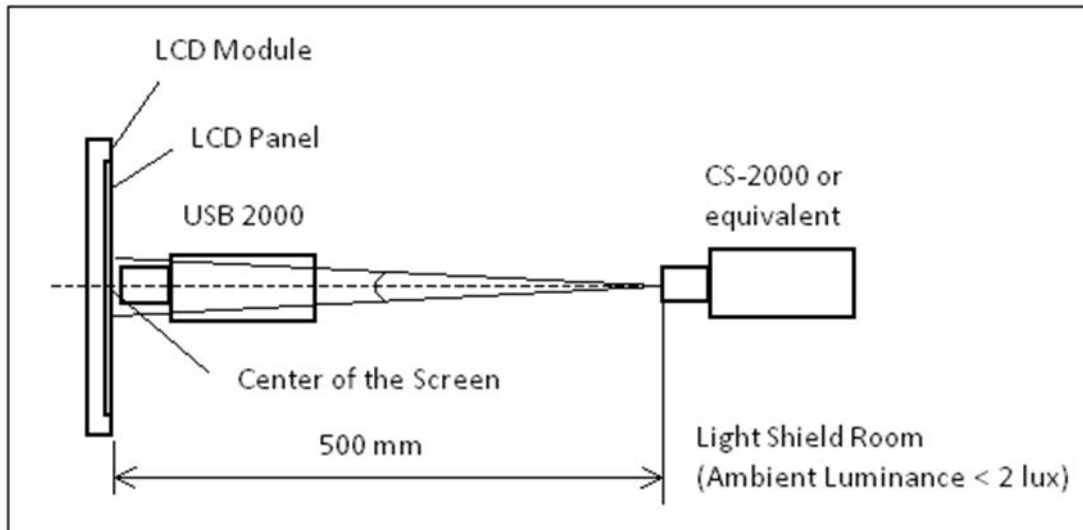


Note (4) Definition of Luminance of White ( $L_c$ ):

Measure the luminance of White at center point.

Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room. The measurement placement of module should be in accordance with module drawing.

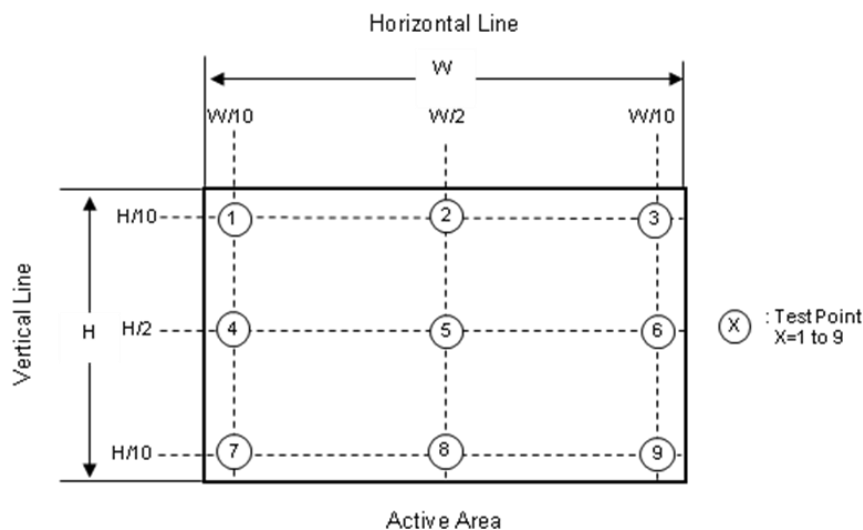


Note (6) Definition of White Variation ( $\delta W$ ):

Measure the luminance of White at 9 points.

Luminance of White :  $L(X)$  , where X is from 1 to 9.

$$\delta W = \frac{\text{Minimum [ } L(1) \text{ to } L(9) \text{]}}{\text{Maximum [ } L(1) \text{ to } L(9) \text{]}} \times 100\%$$



## 8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note
High Temperature Storage Test	80°C, 240 hours	(1),(2) (4),(5)
Low Temperature Storage Test	-30°C, 240 hours	
Thermal Shock Storage Test	-20°C, 0.5 hour ↔ 60°C, 0.5 hour; 100cycles, 1 hour/cycle)	
High Temperature Operation Test	80°C, 240 hours	
Low Temperature Operation Test	-30°C, 240 hours	
High Temperature & High Humidity Operation Test	60°C, RH 90%, 240 hours	(1), (4)
ESD Test (Operation)	150pF, 330Ω, 1 sec/cycle Condition 1 : panel contact, ±8 KV Condition 2 : panel non-contact ±15 KV	
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for ± X, ± Y, ± Z direction	
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz sine wave, 10 min/cycle, 3 cycles each X, Y, Z direction	(2), (3)

Note (1) There should be no condensation on the surface of panel during test ,

Note (2) Temperature of panel display surface area should be 80°C Max.

Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.

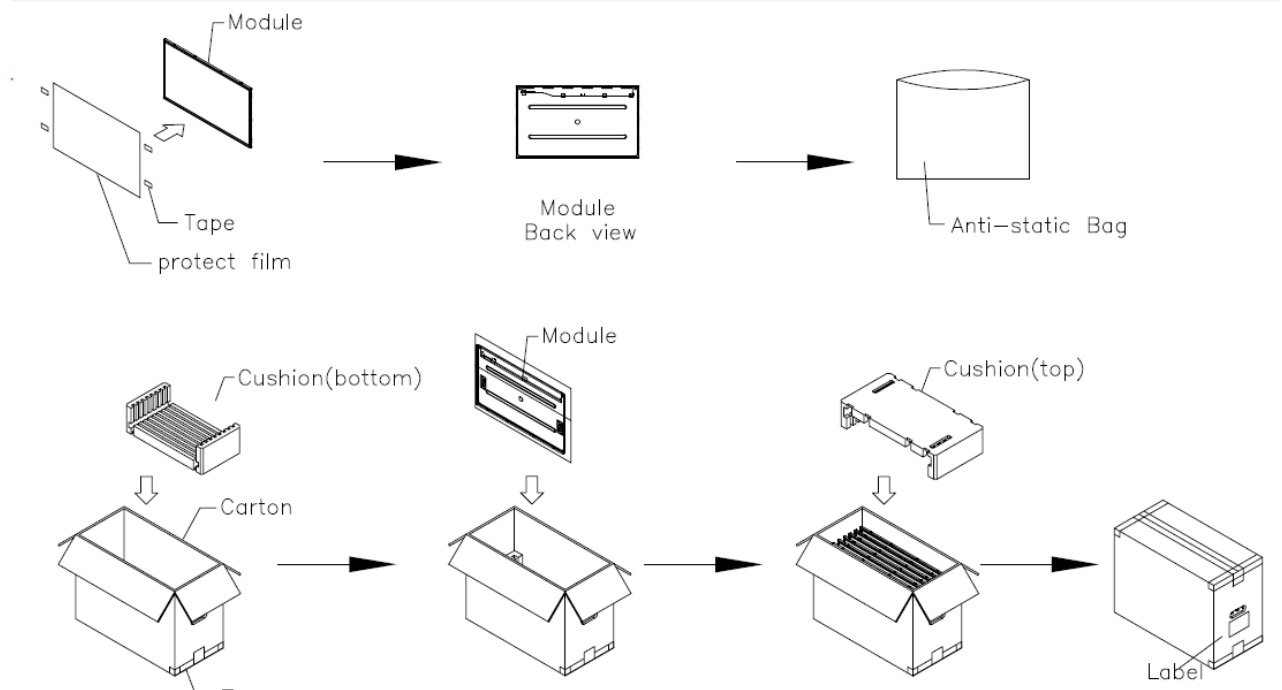
Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.

## 9. PACKAGING

### 9.1 PACKING SPECIFICATIONS

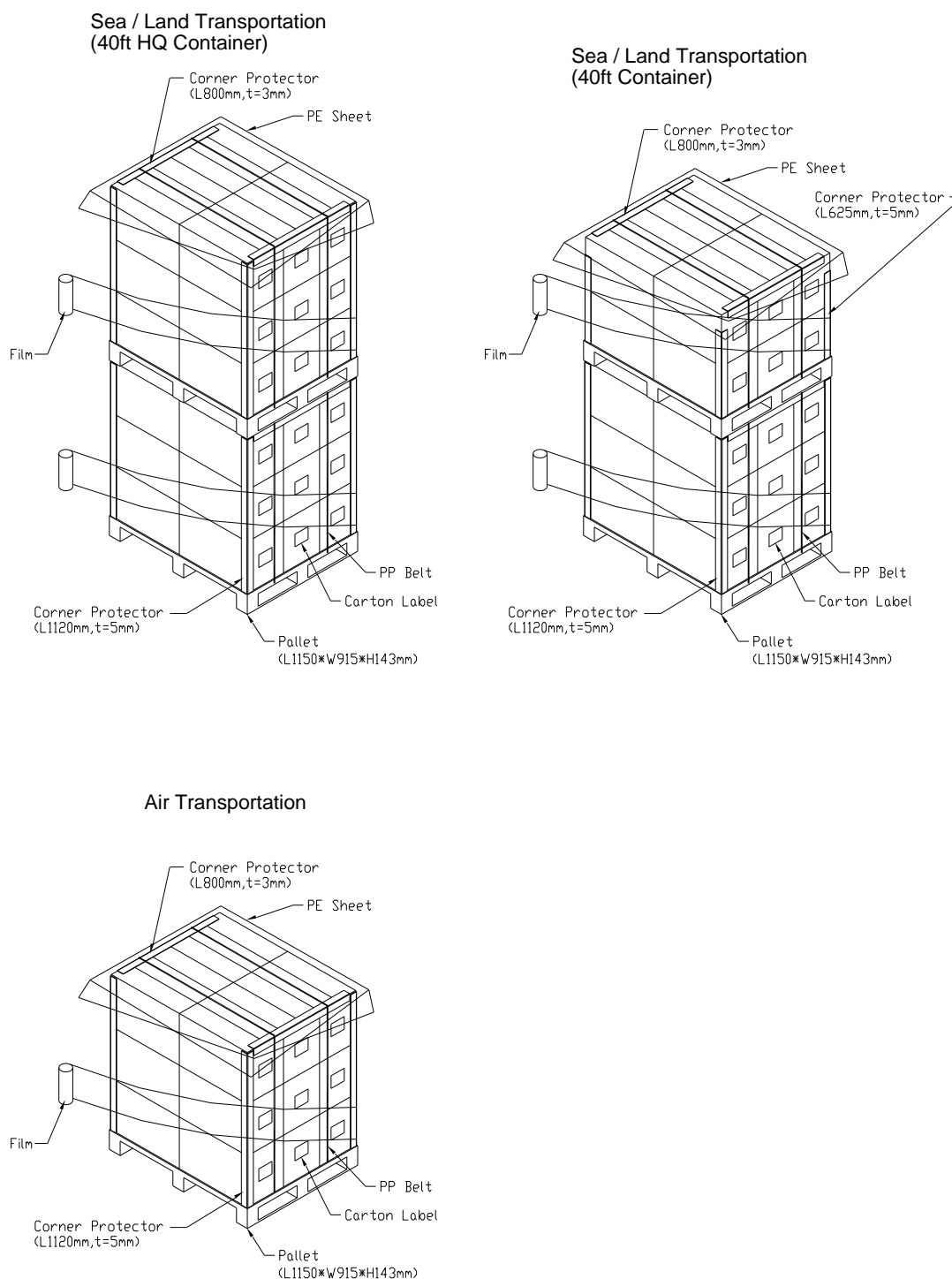
- (1) 8 LCD modules / 1 Box
- (2) Box dimensions: 567(L) X 301(W) X 376(H) mm
- (3) Weight: approximately: 15kg (8 modules per box)

### 9.2 PACKING METHOD



**Figure. 9-1 Packing method**

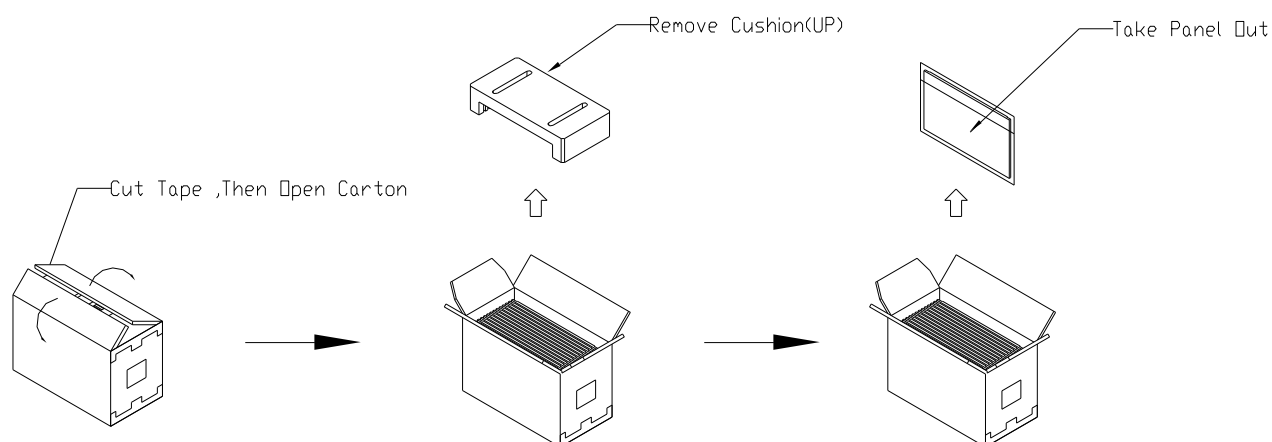




**Figure. 9-2 Packing method**

## 9.3 UN-PACKING METHOD

UN-packaging method is shown as following figures.

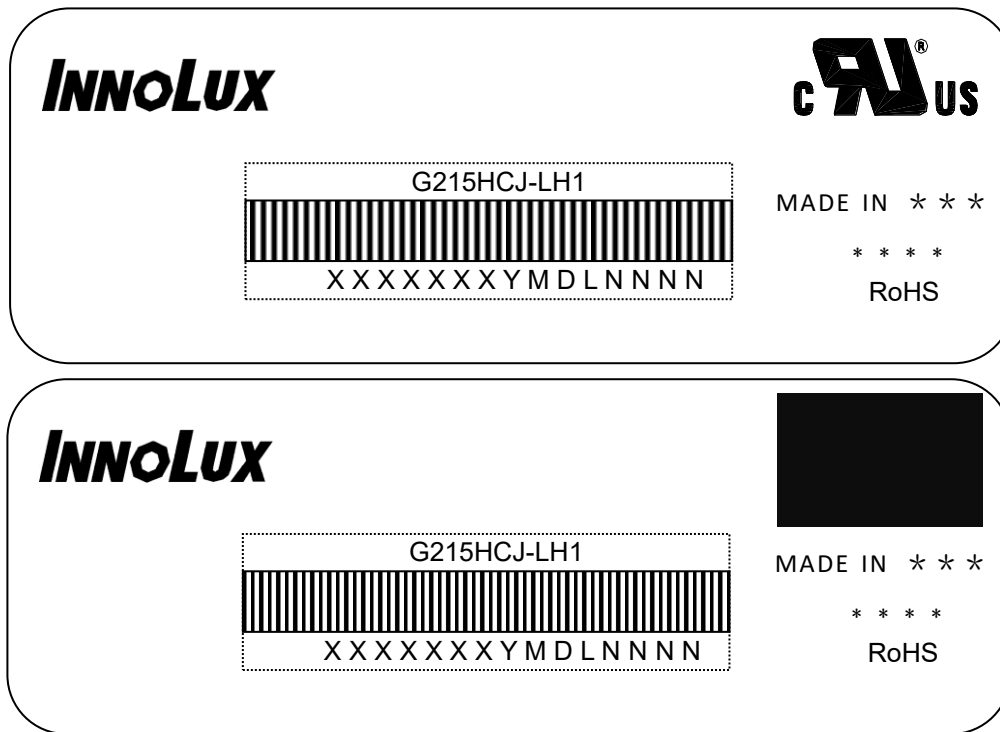


**Figure. 9-3 UN-Packing method**

## 10. DEFINITION OF LABELS

### 10.1 INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.

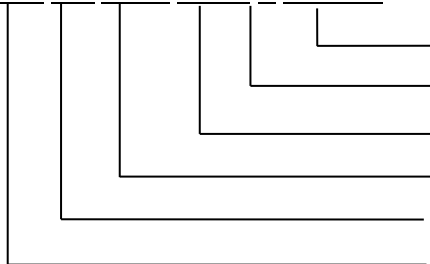


Note (1) Safety Compliance(UL logo) will open after C1 version.

(a) Model Name: G215HCJ-LH1

(b) \* \* \* \* : Factory ID

(c) Serial ID: XXXXXXYMDXXXX



Serial  
INX Internal Use  
Year, Month, Date  
INX Internal Use  
Revision  
INX Internal Use

Serial ID includes the information as below:

(a) Manufactured Date: Year: 1~9, for 2021~2029

Month: 1~9, A~C, for Jan. ~ Dec.

Day: 1~9, A~Y, for 1<sup>st</sup> to 31<sup>st</sup>, exclude I , O and U

(b) Revision Code: cover all the change

(c) Serial No.: Manufacturing sequence of product

## 11. PRECAUTIONS

### 11.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1) The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2) While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3) Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5) If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6) Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9) Do not disassemble the module.
- (10) Do not pull or fold the lamp wire.
- (11) Pins of I/F connector should not be touched directly with bare hands.

### 11.2 STORAGE PRECAUTIONS

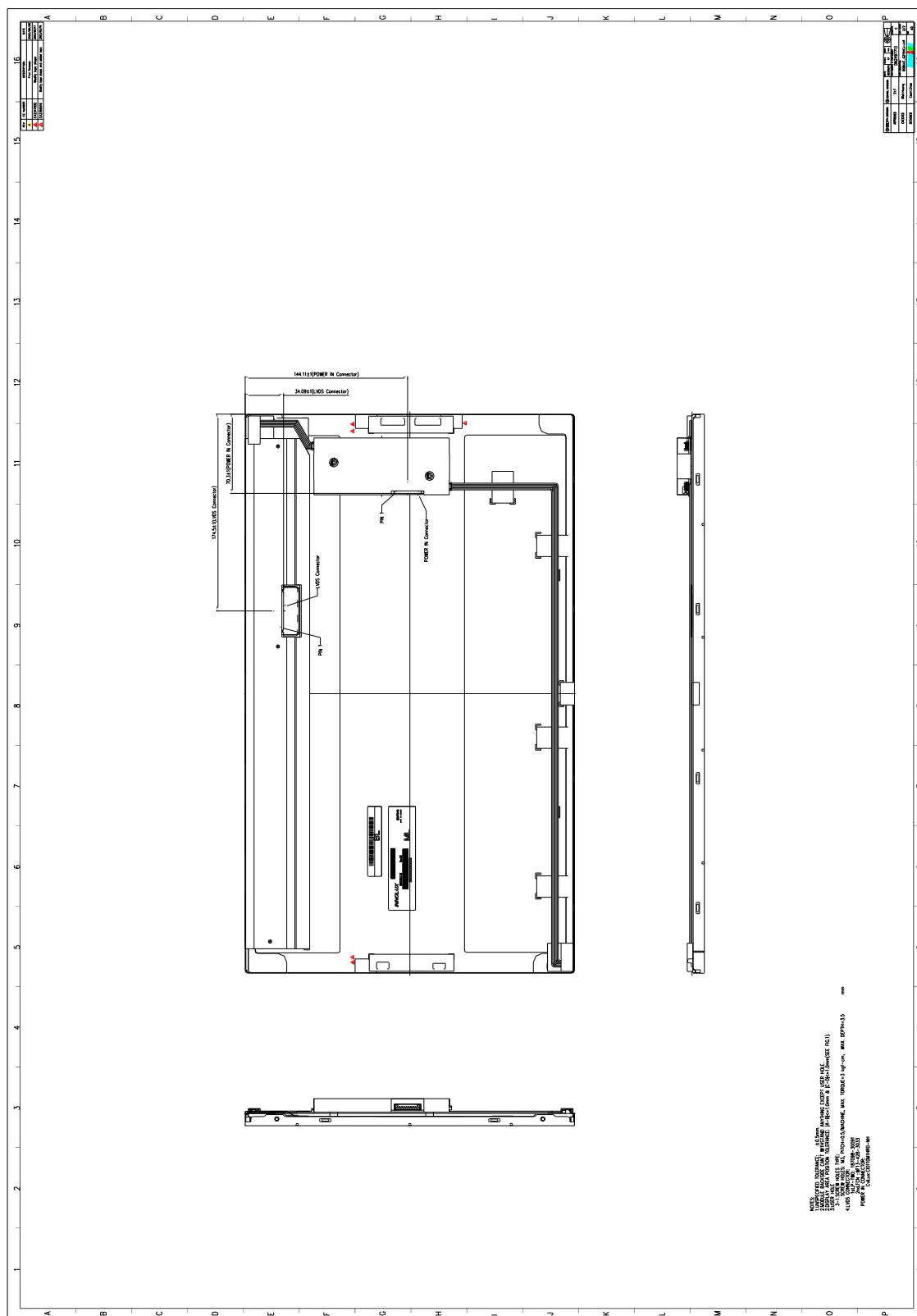
- (1) When storing for a long time, the following precautions are necessary.
  - (a) Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 30°C at humidity 50+-10%RH.
  - (b) The polarizer surface should not come in contact with any other object.
  - (c) It is recommended that they be stored in the container in which they were shipped.
  - (d) Storage condition is guaranteed under packing conditions.
  - (e) The phase transition of Liquid Crystal in the condition of the low or high storage temperature will be recovered when the LCD module returns to the normal condition
- (2) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (3) It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (4) It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of lamp will be higher than the room temperature.
- (5) Storage must be in a fully packaged state (PET bag) and do not expose the sample (module)

## 11.3 OTHER PRECAUTIONS


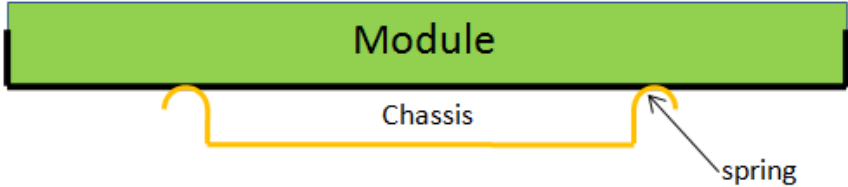
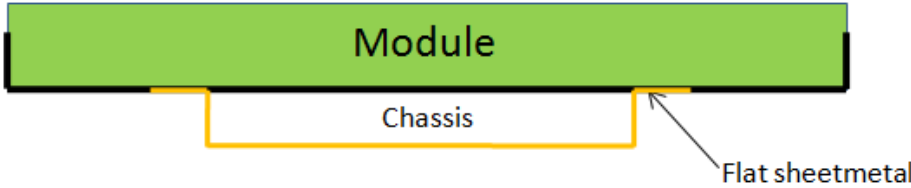
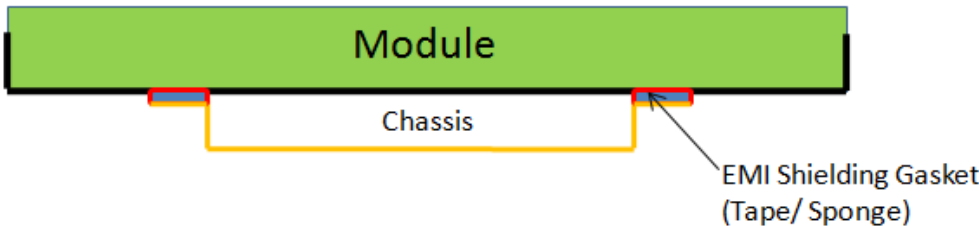
- (1) Normal operating condition
  - (a) Display pattern: dynamic pattern (Real display)
    - (Note) Long-term static display can cause image sticking.
- (2) Operating usages to protect against image sticking due to long-term static display
  - (a) Static information display recommended to use with moving image.
- (3) Abnormal condition just means conditions except normal condition.

## 12. MECHANICAL CHARACTERISTICS

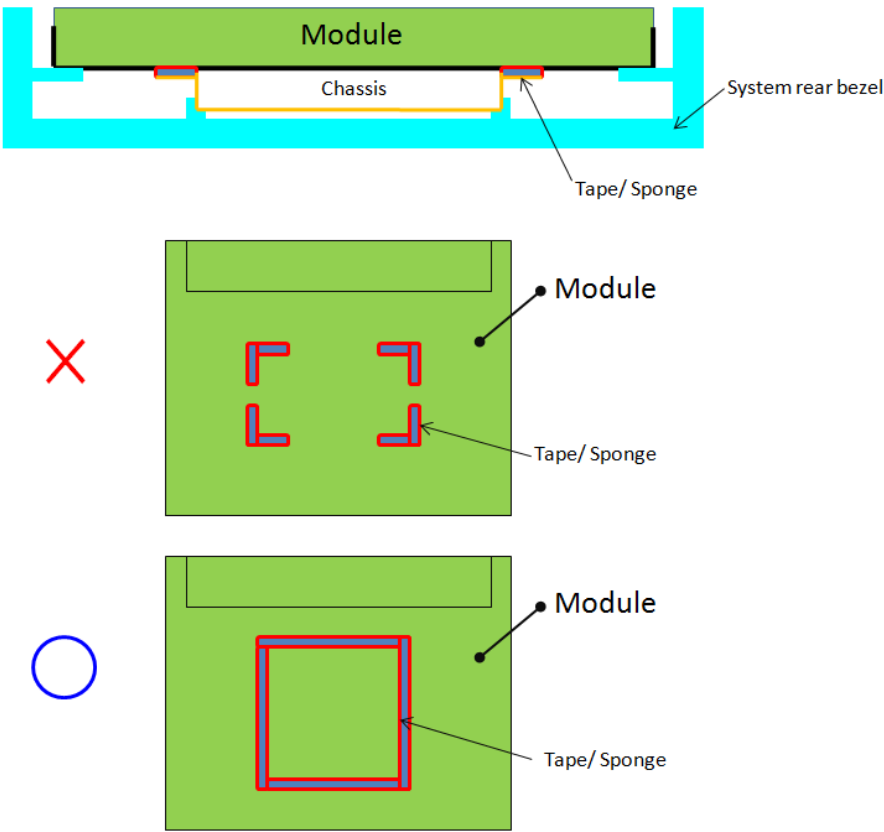


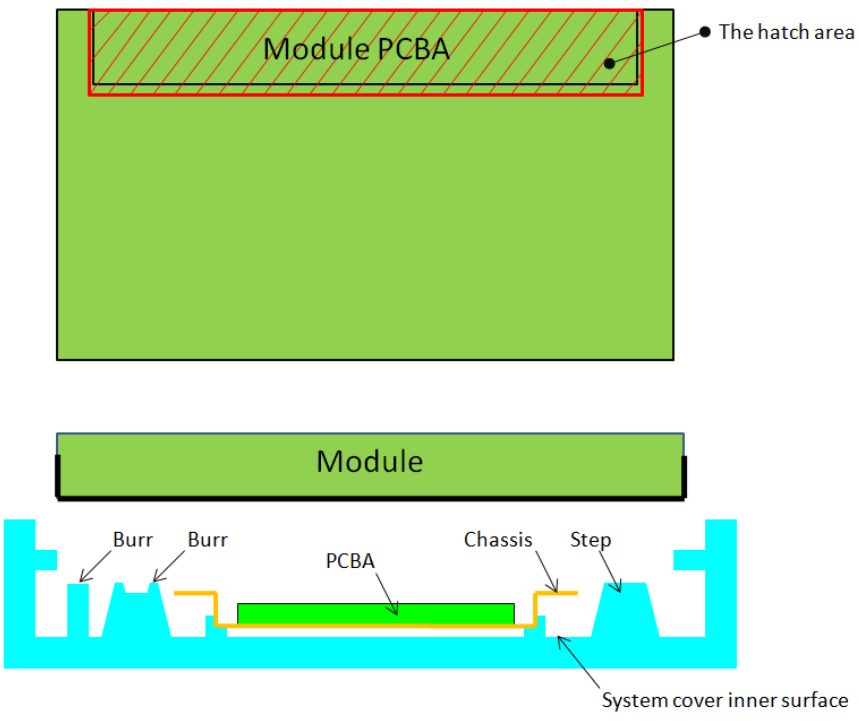


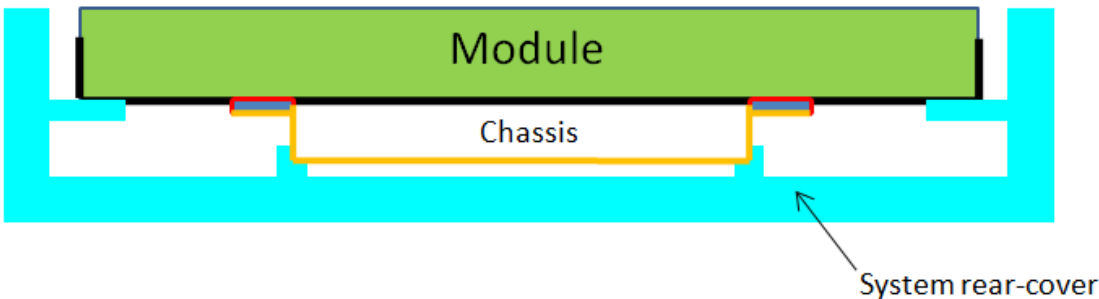
## Appendix. SYSTEM COVER DESIGN NOTICE

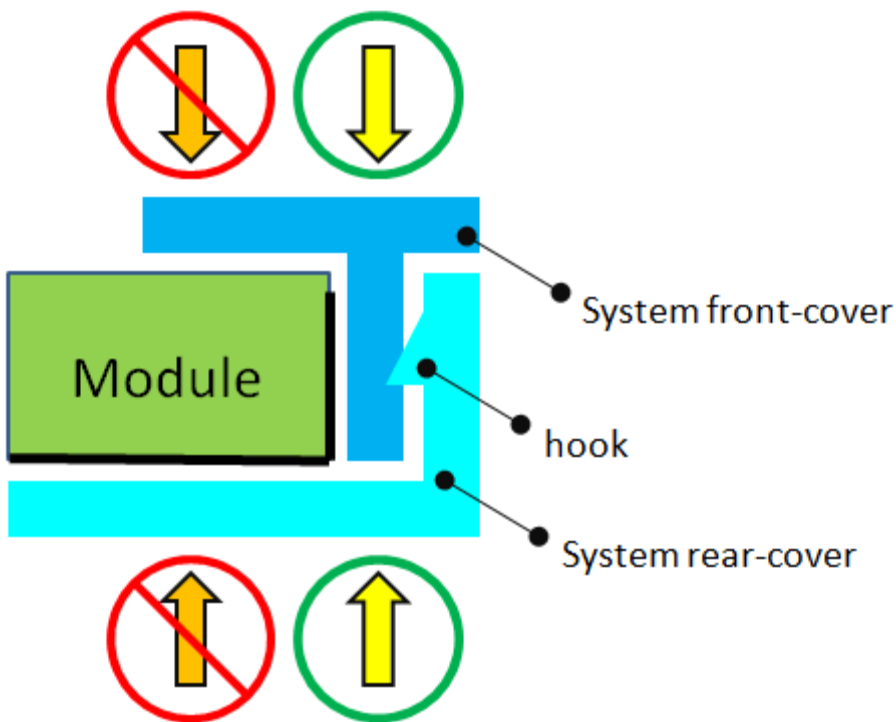
1	Set Chassis and IA Module touching Mode
	  
Definition	<p>a. To prevent from abnormal display &amp; white spot after mechanical test, it is not recommended to use spring type chassis.</p> <p>b. We suggest the contact mode between Chassis and Module rear cover is Tape/Sponge, second is Flat sheet metal type chassis.</p>



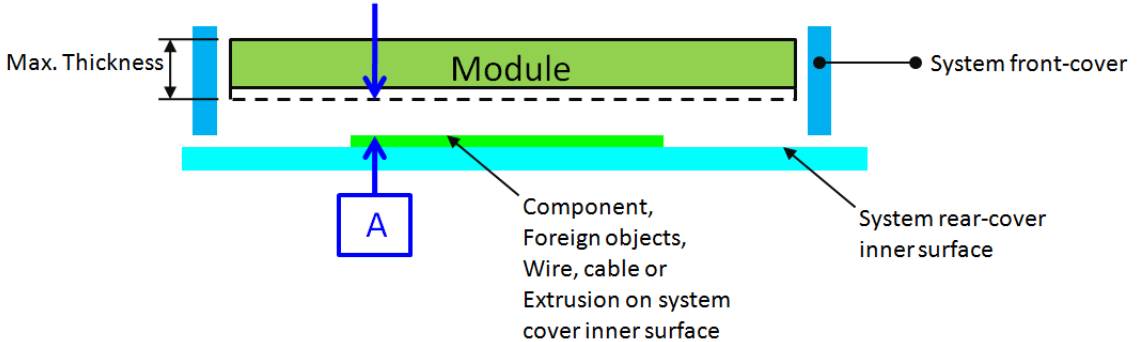
2	Tape/Sponge design on system inner surface
	 <p>The diagrams illustrate the correct and incorrect placement of Tape/Sponge on the system inner surface. The top diagram shows a cross-section of the Module (green) mounted on the Chassis (orange) with the System rear bezel (cyan). The Tape/Sponge (red) is applied between the Module and the Chassis. Below this, two top-down views of the Module are shown. The middle view, marked with a red 'X', shows four separate pieces of Tape/Sponge at the corners. The bottom view, marked with a blue circle, shows a single continuous rectangular piece of Tape/Sponge covering the entire back of the Module.</p>
Definition	<p>a. To prevent from abnormal display &amp; white spot after mechanical test, we suggest using Tape/Sponge as medium between chassis and Module rear cover could reduce the occurrence of white spot.</p> <p>b. When using the Tape/Sponge, we suggest it be lay over between set chassis and Module rear cover. It is not recommended to add Tape/Sponge in separate location. Since each Tape/Sponge may act as pressure concentration location.</p>

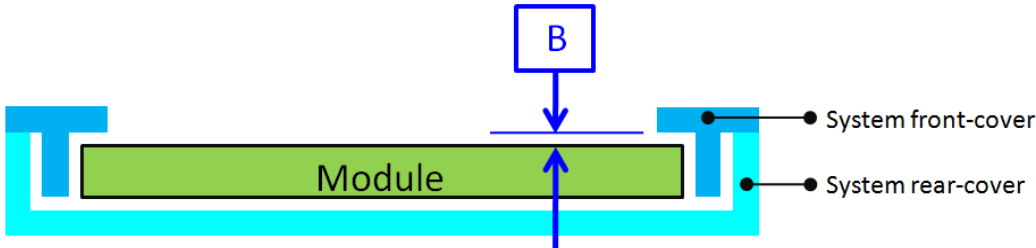
3	System inner surface examination
	 <p>The diagram consists of two parts. The top part is a top-down view of a green rectangular 'Module'. Inside the module, there is a red-outlined rectangular area labeled 'Module PCBA'. Within the PCBA, a smaller area is hatched with red diagonal lines and labeled 'The hatch area'. The bottom part is a cross-sectional view showing the 'Module' (green) mounted on a 'Chassis' (cyan). The 'PCBA' is shown as a green layer on the chassis. 'Burr' and 'Step' features are indicated on the chassis. The 'System cover inner surface' is indicated by a red line.</p>
Definition	<p>a. The hatch area on Module PCBA should keep at least 1mm gap(X,Y,Z direction) to any structure with system cover inner surface.</p> <p>b. Burr, Step, PCB protrusion may cause stress concentration. White spot may occur during reliability test.</p>

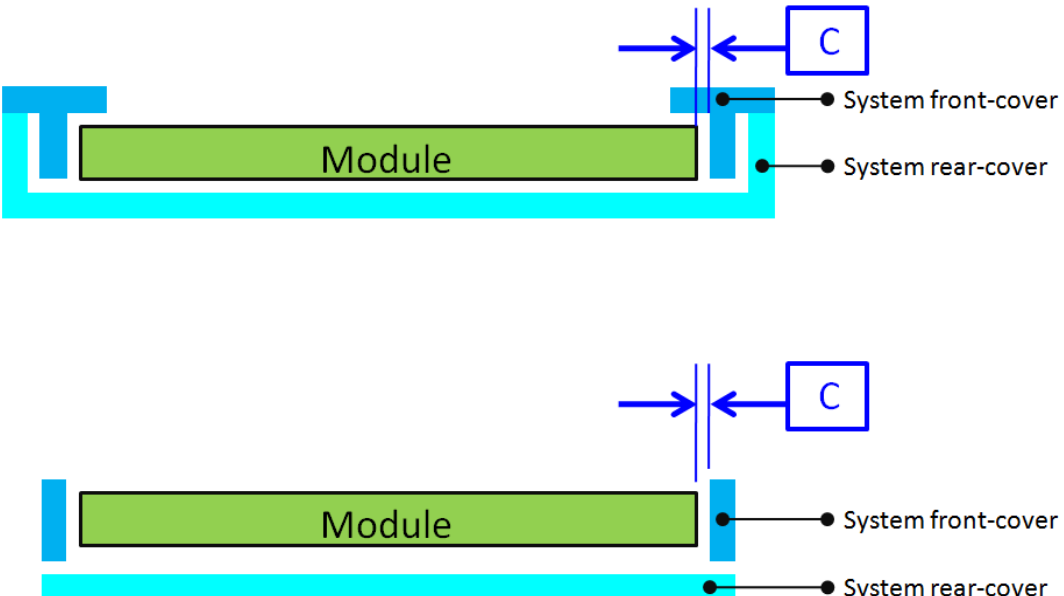
4	Material used for system rear-cover
	
Definition	<p>System rear-cover material with high rigidity is needed to resist deformation during scuffing test, hinge test, pogo test or backpack test. Abnormal display, white spot, pooling issue may occur if low rigidity material is used. Pooling issue may occur because screw's boss position for module's bracket are deformed open-close test.</p> <p>Solid structure design of system rear-cover may also influence the rigidity of system rear-cover. The deformation of system rear-cover should not caused interference.</p>

5	Assembly SOP examination for system front-cover with hook structure
 <p>The diagram shows a green rectangular 'Module' being inserted into a blue 'System front-cover'. The front-cover has a 'hook' structure on its right side. Below the front-cover is a light blue 'System rear-cover'. Four arrows indicate the direction of assembly: a red circle with a downward arrow (prohibited) and a green circle with a downward arrow (recommended) for the front-cover, and a red circle with an upward arrow (prohibited) and a green circle with an upward arrow (recommended) for the rear-cover.</p>	
Definition	To prevent panel crack during system front-cover assembly process with hook structure, it is not recommended to press panel or any location that relate directly to the panel.

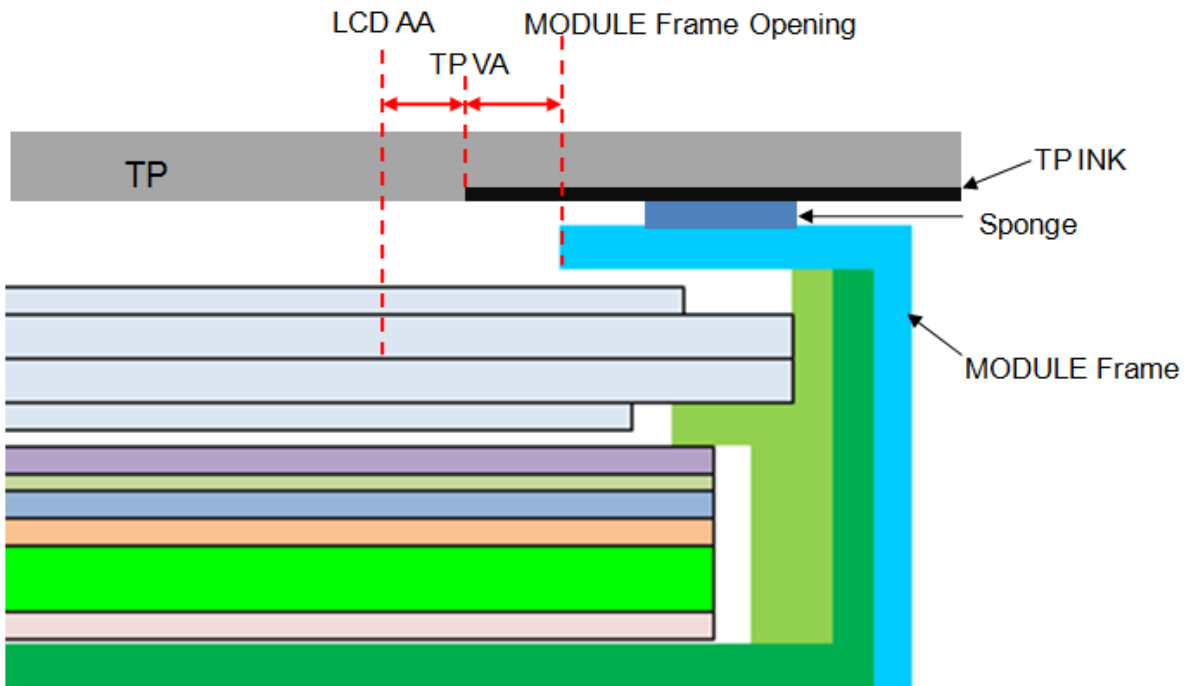
6	Permanent deformation of system cover after reliability test
	<p>The diagrams illustrate various failure modes of system covers after reliability testing. Each diagram shows a green 'Module' between a blue 'System front-cover' and a red 'System rear-cover'. Failure modes are indicated by red 'X' marks and labels: 'deformation' for top/bottom cover warping, '0 gap' for no clearance, and 'deformation' for front cover warping.</p>
Definition	<p>System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell crack.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

7	Design gap A between panel & any components on system rear-cover
	
Definition	<p>System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell creak.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

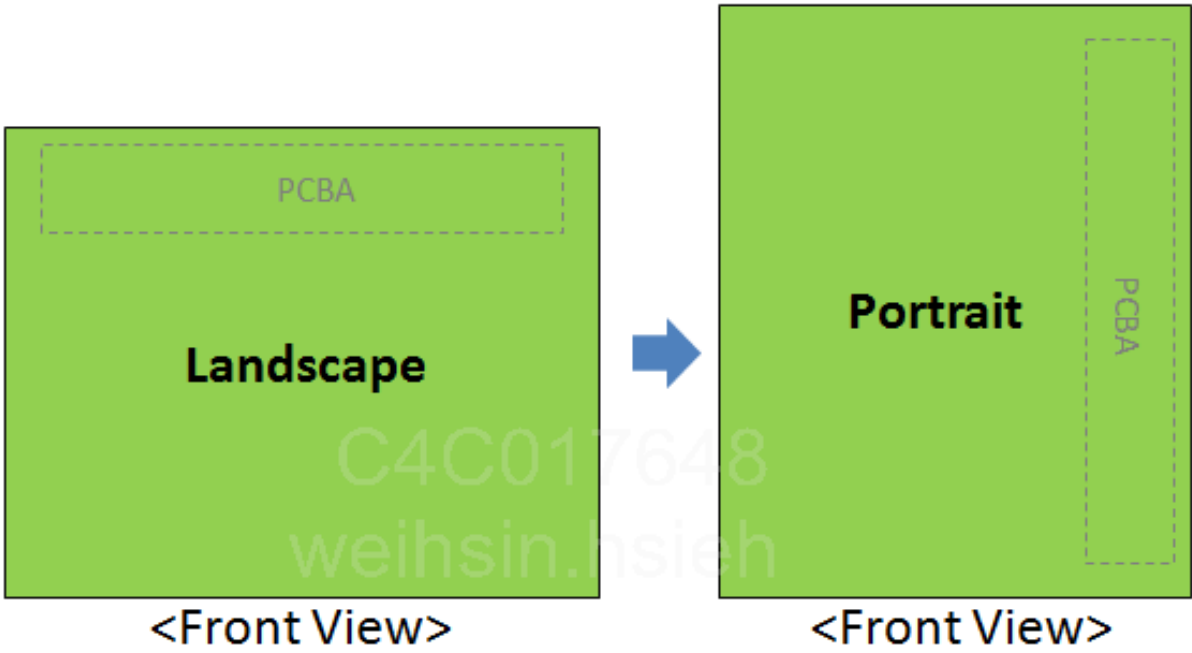
8	Design gap B between system front-cover & panel surface
	
Definition	<p>Gap between system front-cover &amp; panel surface is needed to prevent pooling or glass broken. Zero gap or interference such as burr and warpage from mold frame may cause pooling issue near system front-cover opening edge. This phenomenon is obvious during swing test, hinge test, knock test or during pooling inspection procedure.</p> <p>To remain sufficient gap, design with system rib higher than maximum panel thickness is recommended.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

9	Design gap C between panel & system front-cover or protrusions
 <p>The diagrams illustrate the design gap C between a module and system front-cover or protrusions. The top diagram shows a module (green rectangle) with a system front-cover (blue T-shape) and system rear-cover (blue L-shape). A gap C is indicated between the module and the front-cover. The bottom diagram shows a module (green rectangle) with a system front-cover (blue T-shape) and system rear-cover (blue L-shape). A gap C is indicated between the module and the front-cover.</p>	
Definition	<p>Gap between panel &amp; system front-cover or protrusions is needed to prevent shock test failure. Because system front-cover or protrusions with small gap may hit panel during the test. Issue such as cell crack, abnormal display may occur.</p> <p>The gap should be large enough to absorb the maximum displacement during the test.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>



10	Design distance between TP AA to LCD AA
 <p>The diagram illustrates the cross-section of a display module. At the top is a grey layer labeled 'TP'. Below it is a black layer labeled 'TP INK'. Underneath the TP INK is a blue layer labeled 'Sponge'. The bottom-most layer is a green 'MODULE Frame'. A red dashed line marks the boundary of 'LCD AA'. Another red dashed line marks the 'MODULE Frame Opening'. A red double-headed arrow between these two dashed lines is labeled 'TP VA', indicating the design distance. The TP layer is shown with a cutout to avoid the TP INK area covering the LCD AA or the module frame.</p>	
Definition	TP VA should avoid TP ink area covering LCD AA or causing the module frame to be exposed.

11	Use OCR Lamination
<p>The diagram illustrates the correct use of OCR lamination to avoid line pooling. It shows two cross-sectional views of a display assembly. The top view, marked with a red 'X', shows 'Line pooling' occurring at the edges of the 'Display Area' due to improper OCR application. The bottom view, marked with a green circle, shows the correct application where OCR glue is applied beyond the module edges, and 'Add Side glue' is shown to prevent overflow. Labels include 'Line pooling', 'Display Area', 'TP or Cover Glass', 'OCR', 'TP', 'OCR', 'OCR overflow', and 'Add Side glue'.</p>	
Definition	<p>1.OCR glue as possible beyond module, in order to avoid Line Pooling</p> <p>2.Add side glue to avoid Line Pooling</p>

12	Suggestions for rotation direction from landscape to portrait
 <p>The diagram illustrates the recommended rotation from landscape to portrait orientation. On the left, the 'Landscape' view shows a green rectangle with a dashed box labeled 'PCBA' at the top. A blue arrow points to the right, where the 'Portrait' view is shown. In the portrait view, the green rectangle is oriented vertically, and the dashed box labeled 'PCBA' is positioned on the right side. Both views are labeled '&lt;Front View&gt;' below them.</p>	
Definition	<p>To prevent from abnormal display &amp; white spot after mechanical test, we recommend portrait placement.</p> <p>Note: Please pay attention to the PCBA position after portrait placement.</p>